

9/-29-3

Sheet 1 of 2

FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. HIT 2 925-08	SERIAL NO. 10/671 618
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT J. TANAKA et al	
		FILING DATE 09/29/03	GROUP 2815

U.S. PATENT DOCUMENTS

* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
nbe	AA	5,563,762	10/1996	Leung et al			
	AB	5,117,272	05-1992	Nomura et al			
	AC	5,310,863	05-1994	Sachdev			
	AD	6,071,755	06-2000	Baba et al			
	AE	6,106,906	08-2000	Matsuda et al			
	AF	5,296,716	03-1994	Ovashinsky et al			
	AG	4,132,823	1/2/79	Blackwell et al			
nbe	AH	6,465,827	10/2002	Tanaka et al			
	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
nbe	AL	8-124917	05-1996	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AM	7-278301	10-1995	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AN	07-221259	8/18/95	Japan			<input type="checkbox"/>	<input type="checkbox"/>
nbe	AO	09-293837	11/11/97	Japan			<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

nbe	AR	Lecture Collections in '96 Ferroelectric Film Memory Technique Forum, Science Forum, Inc., page 4-4, lines 1-12, Ishihara, January 26, 1996.
nbe	AS	Epoxy Molding Compounds for Semiconductor Devices, Thermosetting Resins, Vol. 13, No. 4, page 37, right column, lines 8-23, Ogata et al, 1992.
nbe	AT	Packaging Technique for Surface Mount Type LSI Packages and Improvements in Its Reliability, page 451, edited by Hitachi, Ltd.

EXAMINER Jasmine Clark	DATE CONSIDERED 7/21/04
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* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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Sheet 2 of 2

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	AA					
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FOREIGN PATENT DOCUMENTS						
	DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	AL					<input type="checkbox"/> <input type="checkbox"/>
	AM					<input type="checkbox"/> <input type="checkbox"/>
	AN					<input type="checkbox"/> <input type="checkbox"/>
	AO					<input type="checkbox"/> <input type="checkbox"/>
	AP					<input type="checkbox"/> <input type="checkbox"/>
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, etc.)</i>						
ybe	AR	A Study of Package Cracking During the Reflow Soldering Process, "A" Edition, Vol. 55, No. 510, Kitano et al, 1989-2.				
ybe	AS	Effects of Mold Compound Properties on Lead-on-Chip (LOC) Package Reliability During IR Reflow, 1996 Electronic Components and Technology Conference, Yang et al.				
	AT					
EXAMINER			DATE CONSIDERED			
Jasmine Clark			7/21/04			
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